Special Issue

Thermomechanical Sensors

Message from the Guest Editor

Though the study of the physical relationships between heat and motion were started about 300 years ago by James Watt (completely transforming the modern world through the industrial revolution), the use of the heat–motion interplay (thermomechanics) for sensing purposes has gained considerable interest over the last decade thanks to the strong impulse of micro- and nanotechnology. This emerging technology allows a wide range of applications, not only in fundamental science, e.g., in caloritronics, NEMS, energy harvesting, etc., but also in biological research, medical diagnosis, and environmental monitoring. This Special Issue aims to highlight the relevance of thermomechanics in the sensing field. We invite manuscripts for this forthcoming Special Issue on all aspects of thermomechanical sensing, such as development, testing, and modeling of any kind of thermomechanical sensors, advances in fabrication, etc. We look forward to and welcome your participation in this Special Issue.

Guest Editor

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